

# APPROVAL SHEET

# WW12R, WW08R, WW06R

±1%, ±5%

Metal Low Ohm Power Chip Resistors Size 1206 (1W), 0805 (0.5W), 0603 (0.33W) RoHS Exemption free and Lead free Sensing Type



#### **FEATURE**

- 1. Metal ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS exemption free & Halogen free & Lead free
- 6. Inductance below 1nH

#### **APPLICATION**

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

#### **DESCRIPTION**

The resistors are constructed in a high grade low resistive metal body. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead free terminations.



Fig 1. Construction of Chip-R



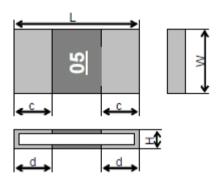
#### **QUICK REFERENCE DATA**

Item		General Specification			
Series No.	WW06R	WW06R WW08R			
Size code	0603 ( 1608 ) 0805 ( 2012 )		1206 (3216)		
Resistance Tolerance	±5% , ±1%				
Resistance Range	5, 10mΩ	2, 3, 4, 5, 6, 7, 8, 9 10mΩ,	1 ~ 15 mΩ		
TCR (ppm/°C)	±70 ppm/°C				
Max. power at T <sub>amb</sub> =70°C	1/3 W	1/2 W	1W		
Max. Operation Current (DC or RMS)	8.1A, 5.7A	7A ~ 15.8A	31.6A ~ 8.2A		
Operation temperature	-55 ~ +155°C				

Note: Max. Operation Current: So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$  listed above.

#### **MECHANICAL DATA**



Unit: mm

Туре	Size (inch)	Resistance	L (mm)	W (mm)	H (mm)	c (mm)	d (mm)
MUMOCD	0000	5mΩ		0.00-0.40	0.33±0.10	0.20±0.10	0.50±0.10
WW06R	0603	10mΩ	1.60±0.10	1.60±0.10	0.30±0.10	0.20±0.10	0.30±0.10
		2mΩ			0.22±0.10	0.35±0.10	0.55±0.20
		3mΩ		1.25±0.15	0.45±0.10	0.35±0.10	0.75±0.20
		4mΩ	2.0±0.15		0.35±0.10	0.35±0.10	0.75±0.20
	0805	5mΩ			0.35±0.10	0.35±0.10	0.60±0.20
WW08R		6mΩ			0.35±0.10	0.35±0.10	0.47±0.20
		7mΩ			0.22±0.10	0.35±0.10	0.75±0.20
		8mΩ			0.22±0.10	0.35±0.10	0.60±0.20
		9mΩ			0.22±0.10	0.35±0.10	0.52±0.20
		10mΩ			0.22±0.10	0.30±0.10	0.47±0.20
WW12R	1206	1mΩ	3.2±0.15	1.60±0.15	0.32±0.10	1.10	±0.25

2mΩ		0.32±0.10	0.50±	±0.25
3mΩ		0.35±0.10	0.70±0.25	1.30±0.25
4mΩ		0.35±0.10	1.10±	<b>±0.25</b>
5mΩ		0.35±0.10	1.00±	<b>±0.25</b>
6mΩ		0.35±0.1	0.80	±0.25
7mΩ		0.35±0.1	0.70	±0.25
8mΩ		0.35±0.1	0.50±	±0.25
9mΩ		0.28±0.1	0.55±	±0.25
10mΩ		0.28±0.1	0.50±	±0.25
11mΩ		0.22±0.1	0.80±	±0.25
12mΩ		0.22±0.1	0.70±	±0.25
13mΩ		0.22±0.1	0.60±	±0.25
14mΩ		0.22±0.1	0.55±	±0.25
15mΩ		0.22±0.1	0.50±	±0.25

#### **MARKING**

WW12R/WW08R each resistor is marked with a 2-digit code with underline on the protective coating to designate the nominal resistance value. WW06R has no marking!

Example:

 $\frac{05}{10} = 0.005\Omega$  $\frac{10}{10} = 0.010\Omega$ 

#### **FUNCTIONAL DESCRIPTION**

#### **Derating curve**

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

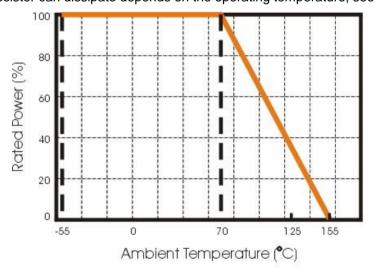


Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature



#### **SOLDERING CONDITIONS**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 245°C during 3 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig

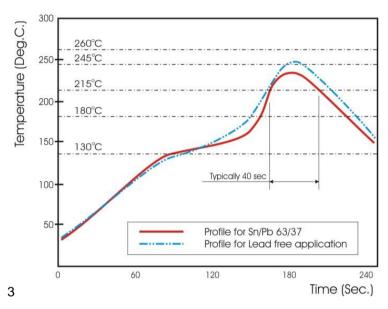


Fig 3. Infrared soldering profile for Chip Resistors WWxxR

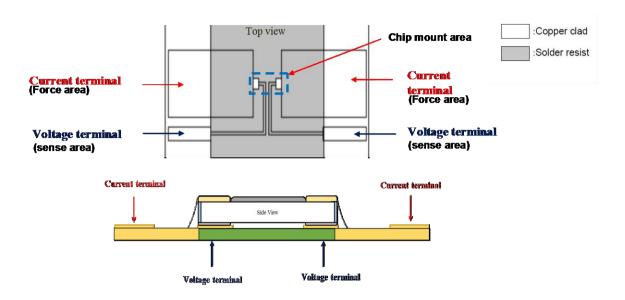
#### **CATALOGUE NUMBERS**

The resistors have a catalogue number starting with .

WW06	R	R005	J	Т	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WW06 : 0603	R : 1/3W, 0603	R is first digit followed by 3	J : ±5%	T:7" reel	L = Sn base
WW08 : 0805	1/2W, 0805	significant digits.	F:±1%	Q : 10" reel	(lead free)
WW12 :1206	1W, 1206	$0.010\Omega = R010$			
		$0.005\Omega = R005$			

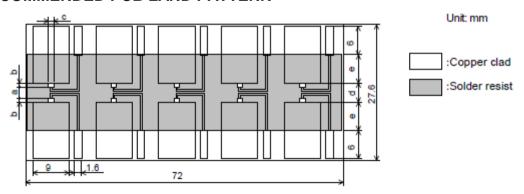
Reeled tape packaging : 8mm width paper taping 5,000pcs per 7" reel. 10,000pcs per 10" reel.

#### RESISTANCE MEASUREMENT SCHEMATIC DIAGRAM



The resistance measured is based on mounted on PCB to match with customer field application.

#### RECOMMENDED PCB LAND PATTERN



Style	Rated resistance (mΩ)	a	b	С	d	е
WW06R	5	0.6	0.9	0.9	2.2	6.2
L TTTOOK	10	1.0	0.6	0.9	2.2	6.2
WW08R	2,3	0.5	1.1	4.20	2.7	5.95
WWook	4 to 10	0.8	0.95	1.36	2.1	5.95
	1	1.0	1.45			
	2	2.1	0.9			
WW12R	3	0.8	1.55	1.7	3.9	5.35
	4	1.0	1.45	1.7	3.9	5.35
	5 and 6	1.4	1.25			
	7 to 15	2.1	0.9			

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



## **TEST & REQUIREMENTS**

Table-4(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements
		, ,	•
1	Visual examination	Sub-clause 4.4.1	As in 4.4.1
		Checked by visual examination.	The marking shall be legible, as
			checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this
			specification.
	Resistance	Resistance value shall be measured by mounting	As in 4.5.2
		the substrate of the following condition.	The resistance value shall
		3	correspond with the rated resistance
		Current Current	taking into account the specified
		terminal	tolerance.
		Copper dad Voltage terminal Solder resist	
		a: 2.9mm (2m Ω , 3mΩ, 4m Ω ),	
		1.8mm (5m Ω)	
		Thickness of copper clad: 0.035mm	
		4-Terminal method	
		Measurement current: 1(A)	
		Note:The measuring apparatus corresponding to	
		DC Low-ohm Mater (1A) of AX-1152D for ADEX	
		CORPORATION.	
3	Voltage proof	Sub-clause 4.7	
		Method: 4.6.1.4(See Figure-5)	No breakdown or flash over
		Test voltage: Alternating voltage with a peak value	
		of 1.42 times the insulation voltage.	
		Duration: 60 s±5 s	
		Insulation resistance	
		Test voltage: Insulation voltage	R≥1GΩ
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
		Without aging	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non–activated soldering flux for 2 s.	coating.
		Bath temperature: 235 °C±5 °C	
		Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Overload	Sub-clause 4.13	
	(in the mounted state)	The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s	
		Visual examination	No visible damage
		Resistance	ΔR≤±1%
	Solvent resistance of the	Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
	1	1	i .

Table-4(2)

	Table–4(2)					
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements			
6	Mounting	Sub-clause 4.31				
		Substrate material: Epoxide woven glass				
		Test substrate: Figure-4				
	Bound strength of the end	Sub-clause 4.33				
	face plating	Bent value: 1 mm				
		Resistance	$\Delta R \le \pm 1\%$			
	Final measurements	Sub-clause 4.33.6				
		Visual examination	No visible damage			
7	Resistance to soldering heat	Sub-clause 4.18				
		Solder temperature: 260 °C±5 °C				
		Immersion time: 10 s±0.5 s				
		Visual examination	As in 4.18.3.4			
			No sign of damage such as cracks.			
		Resistance	ΔR≤±1%			
	Component solvent	Sub-clause 4.29				
	resistance	Solvent: 2-propanol				
		Solvent temperature: 23 °C±5 °C				
		Method 2				
		Recovery: 48 h	No della desse			
		Visual examination	No visible damage			
		Resistance	ΔR≤±1%			
8	Mounting	Sub-clause 4.31				
		Substrate material: Epoxide woven glass				
	Adhasian	Test substrate: Figure–3				
	Adhesion	Sub-clause 4.32				
		Force: 5 N				
		Duration: 10 s±1 s	No visible damage			
	Rapid change temperature	Visual examination	140 visible dalllage			
	rapid change temperature	Sub-clause 4.19				
		Lower category temperature:-55 °C				
		Upper category temperature:+155 °C				
		Duration of exposure at each temperature: 30				
		min.				
		Number of cycles: 5 cycles.	No visible damage			
		Visual examination	ΔR≤±1%			
		Resistance	AK2170			

Table-4(3)

	Table-4(5)						
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements				
9	Climatic sequence	Sub-clause 4.23					
	-Dry heat	Sub-clause 4.23.2					
		Test temperature: +155 °C					
		Duration: 16 h					
	-Damp heat, cycle	Sub-clause 4.23.3					
	(12+12hour cycle)	Test method: 2					
	First cycle	Test temperature: 55 °C					
		[Severity(2)]					
	-Cold	Sub-clause 4.23.4					
		Test temperature –55 °C					
		Duration: 2h					
	-Damp heat, cycle	Sub-clause 4.23.6					
	(12+12hour cycle)	Test method: 2					
	Remaining cycle	Test temperature: 55 °C					
		[Severity (2)]					
	–D.C. load Number of cycles: 5 cycles Sub–clause 4.23.7						
		The applied current shall be the rated current.					
		Duration: 1 min.					
		Visual examination	No visible damage				
		Resistance	∆R≤±(1%+0.0005ohm)				
10	Mounting	Sub-clause 4.31					
		Substrate material: Epoxide woven glass					
		Test substrate: Figure-3					
	Endurance at 70 °C	Sub-clause 4.25.1					
		Ambient temperature: 70 °C±2 °C					
		Duration: 1000 h					
		The current shall be applied in cycles of 1.5 h					
		on and 0.5 h.					
		The applied current shall be the rated current					
		Examination at 48 h, 500 h and					
		1000 h:					
		Visual examination	No visible demage				
		Resistance	No visible damage				
			∆R≤(1%+0.0005ohm)				

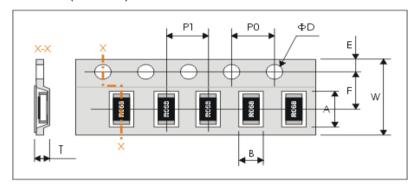


Table-4(4)

	Table—4(4)					
No	Test items	Condition of test (JIS C 5201-1)	Performance requirements			
11	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3				
	Variation of resistance with temperature	Sub-clause 4.8 +20 °C / +155 °C	As in Table–1			
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3				
	Damp heat, steady state	Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination	No visible damage Legible marking			
		Resistance	ΔR≤±(1%+0.0005ohm)			
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–4			
	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3				
	Endurance at upper category temperature	Sub-clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage ∆R≤±(1%+0.0005ohm)			

#### **PACKAGING**

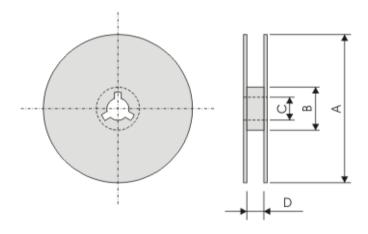
#### Paper Tape specifications (unit :mm)



Symbol	Α	В	W	F	E
WW06R	1.90±0.20	1.15±0.15		3.50±0.05	1.75±0.10
WW08R	2.50±0.20	1.65±0.15	8.00±0.20		
WW12R	3.60±0.20	2.00±0.15			

Symbol	P1	P0	ΦD	Т
WW06R		4.00±0.10	Ф1.50 <sup>+0.1</sup>	0.8 max.
WW08R	4.00±0.10			1.0 max.
WW12R				1.0 max.

#### **Reel dimensions**



Symbol	Α	В	С	D
7"	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	9.0 +1.0
10"	Φ254.0 ±2.0	Φ100.0±1.0	13.0±0.2	9.0 +1.0

### **Taping quantity**

- Chip resistors 5,000 pcs per 7" reel; 10,000pcs per 10" reel.